# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**  
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>Name / Model #1</th>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>HP EliteBook 2760p Notebook PC</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Name / Model #2</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Name / Model #3</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Name / Model #4</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Name / Model #5</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Yes</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Yes</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries No</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Yes</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. No</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td>No</td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances | No | 0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>T8 Torx</td>
<td>T8</td>
</tr>
<tr>
<td>Cross</td>
<td>#1</td>
</tr>
<tr>
<td>Slot</td>
<td>2.5*50</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Took off the battery module and bottom door
2. Took off HDD module/hinge cover
3. Loosed KB screws and took off KB module
4. Took off upper case and VGA half cover
5. Took out antenna/LVDS/MIC cables
6. Took off hinge-up assembly and MB shielding
7. Took off smart card and MB assembly from base system
8. Loosed screws and took off display bezel
9. Took off jog dial/convertor board
10. Took off hinge cap/CVR covers and loosed hinge screws
11. Took off display rubber and loosed screws
12. Took off LVDS/digitizer connector cables

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Outfield Project Tear Down Report

ME: Yueh Han
Date: 2011/04/11
Step 1: Took off the battery module and bottom door

1. Released battery knob and took off the battery module.
2. Loosed three screws on bottom door and took off the bottom door.
**Step 2:** Took off HDD module/hinge cover

1. Loosed two screws on HDD bracket.

2. Loosed two screws on hinge cover and took off the hinge cover.
Step 3: Loosed KB screws and took off KB module

1. Loosed five KB screws and four upper case screws on bottom side.

2. Reversed the system and took off keyboard module.
Step 4: Took off upper case and VGA half cover

1. Loosed two upper case screws and took out volume/touchpad FFC.

2. Took off upper case and VGA half cover.
Step 5: Took out antenna/LVDS/MIC cables

1. Took out all antenna cables and MIC cable from bottom side.
2. Rotated hinge-up assembly and took off LVDS connector cable.
3. Loosed four hinge screws on base system.
Step 6: Took off hinge-up assembly and MB shielding

1. Took off hinge-up assy. from base system.
2. Loosed four MB shielding screws.
3. Took off MB shielding from system. (Took care two points hooks structure.)
Step 7: Took off smart card and MB assembly from base system

1. Took off smart card module and took out audio FFC.

2. Loosed one MB screw and took off MB assy. from base system.
Step 8: Loosed screws and took off display bezel

1. Loosed two screws on display bezel.
2. Took off display bezel from hinge-up assy.
Step 9: Took off jog dial/converter board
1. Loosed two jog dial board screws and three converter board screws.
2. Took out converter connector cable and KB light combo FFC.
3. Took out hinge bumpers on panel cover assy.
**Step 10:** Took off hinge cap/CVR covers and loosened hinge screws

1. Took off hinge cap/CVR covers on panel cover assy.

2. Loosened six center hinge screws on panel cover assy.
**Step11:** Took off display rubber and loosed screws

1. Took off display rubber on LCD frame.

2. Loosed LCD frame eleven screws on panel cover assy.
Step 12: Took off LVDS/digitizer connector cables

1. Took off LVDS connector cable and digitizer connector cable.
2. Took off LCM assembly from panel cover assy.
Thank You!